



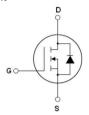
N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- ◆ New technology for high voltage device
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ROHS compliant





Schematic diagram

TO-220F

Application

- ◆ Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- ◆ Uninterruptible Power Supply (UPS)

Vos	650	V
R _{DS(ON)TYP}	680	mΩ
ID	7	А

Package Marking And Ordering Information

Device Device Package		Marking	
MJ65T680F	TO-220F	MJ65T680F	

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ65T680F	Unit	
Drain-Source Voltage (Vss=0V)	VDS	650	V	
Gate-Source Voltage (Vps=0V) AC (f>1 Hz)	Vgs	±30	V	
Continuous Drain Current at Tc=25°C	ID (DC)	7*	А	
Continuous Drain Current at Tc=100°C	ID (DC)	4.5*	А	
Pulsed drain current (Note 1)	IDM (pluse)	28*	А	
Maximum Power Dissipation (Tc=25°C)	Po	31.4	W	
Derate above 25°C	PD	0.25	W/°C	
Single pulse avalanche energy (Note 2)	Eas	101	mJ	
Avalanche current (Note 1)	lar	1.5	А	
Repetitive Avalanche energy, t_{AR} limited by T_{jmax} (Note 1)	Ear	0.28	mJ	

Parameter	Symbol	MJ65T680F	Unit
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T _J ,Tsтg	-55+150	°C





Table 2. Thermal Characteristic

Parameter	Symbol	MJ65T680F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	3.98	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	80	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	'					
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250μA	650	-	-	V
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V _{DS} =650V,V _{GS} =0V	-	_	1	μΑ
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	100	μΑ
Gate-Body Leakage Current	lgss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	-	4	V
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =10V,I _D =3.5A	-	680	760	mΩ
Dynamic Characteristics	1					
Input Capacitance	Cies	- 43		435	-	PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	28	-	PF
Reverse Transfer Capacitance	Crss	-	-	3.3	-	PF
Total Gate Charge	Qg		-	11	-	nC
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =7A V _{GS} =10V		3.5	-	nC
Gate-Drain Charge	Qgd	-	-	5	-	nC
Switching times						
Turn-on Delay Time	t _{d(on)}		-	8	-	nS
Turn-on Rise Time	tr	VDD=380V,ID=3.5A	-	7	-	nS
Turn-Off Delay Time	t _{d(off)}	R _G =4.7Ω,V _G s=10V	-	58	75	nS
Turn-Off Fall Time	tr	-	-	9	15	nS
Source- Drain Diode Characteristics						
Source-drain current (Body Diode)	Isp		-	-	7	А
Pulsed Source-drain current (Body Diode)	Isdm	- Tc=25°C	-	-	28	А
Forward On Voltage	Vsp	T _j =25°C,I _{SD} =7A,V _{GS} =0V	-	0.9	1.2	V
Reverse Recovery Time	trr		-	210	-	nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=3.5A di/dt=100A/µs	-	0.85	-	uC
Peak reverse recovery Current	Irrm	Irm - 8 -			-	А

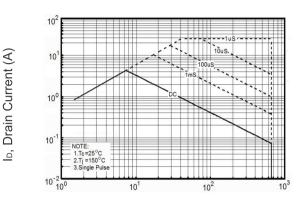




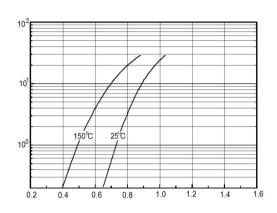
Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j = 25^{\circ}C, V_{DD} = 50V, V_{G} = 10V, R_{G} = 25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

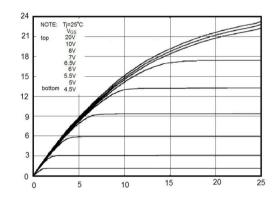


lor, Reverse Drain Current(A)



V_{DS}, Drain-Source Voltage (V)

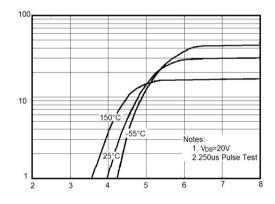
Figure 1 Safe operating area



lb, Drain Current (A)

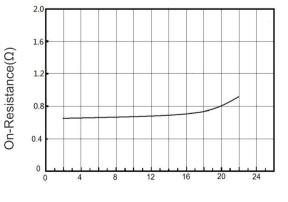
Vsp,Source-Drain Voltage(V)

Figure 2 Source-Drain Diode Forward Voltage



V_{DS}(V)

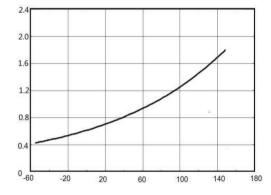
Figure 3 Output characteristics



RDS(ON), Drain-Source

R_{DS(ON)}, Drain-Source On-Resistance(Ω)

V_{GS}, Gate-Source Voltage (V) Figure 4 Transfer characteristics



ID, Drain Current (A)

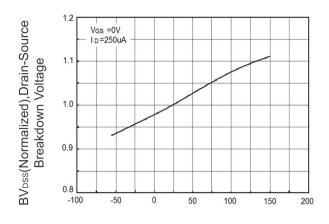
Figure 5 Static drain-source on resistance

T_J, Junction Temperature (°C) Figure 6 RDS(ON) vs Junction Temperature

Ib, Drain Current (A)

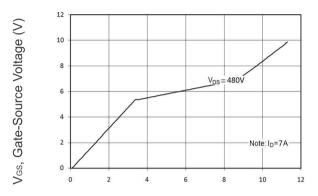
Capacitances(pF)





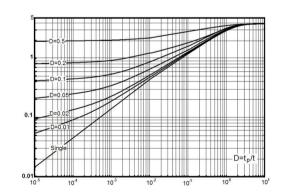
T_J, Junction Temperature (°C)

Figure 7 BVDSS vs Junction Temperature



Q_G,Total Gate Charge(nC)

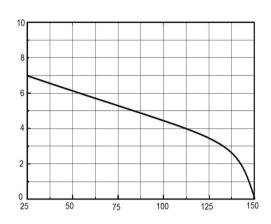
Figure 9 Gate charge waveforms



Zthuc, Thermal Respone

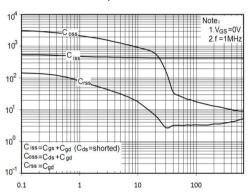
tp,Square Wave Pulse(S)

Figure 11 Transient Thermal Impedance



Tc, Case Temperature (°C)

Figure 8 Maximum ID vs Junction Temperature



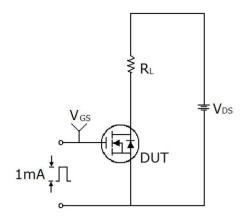
V_{DS}, Drain-Source Voltage (V)

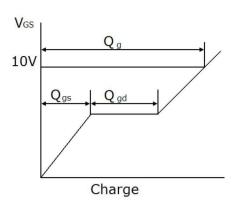
Figure 10 Capacitance



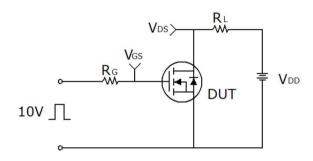


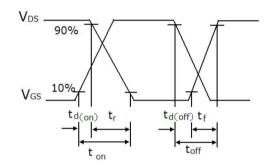
Test circuit



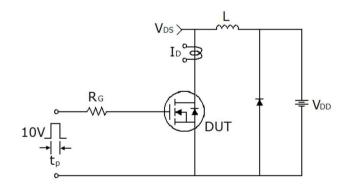


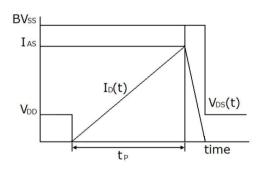
Gate charge test circuit & Waveform





Switch Time Test Circuit



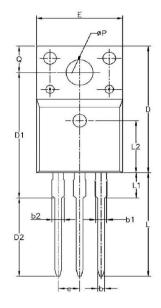


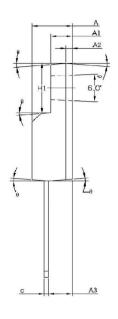
Unclamped Inductive Switching Test Circuit & Waveforms

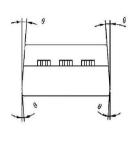




TO-220F Package Information

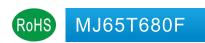






Ormak al	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.500	4.830	0.177	0.190
A1	2.340	2.740	0.092	0.108
A2	0.700	REF.	0.028	REF.
A3	2.560	2.930	0.101	0.115
b	0.700	0.900	0.028	0.035
b1	1.180	1.380	0.046	0.054
b2	-	1.47	-	0.058
С	0.450	0.600	0.018	0.024
D	15.670	16.070	0.617	0.633
D1	15.550	15.950	0.612	0.628
D2	9.600	10.000	0.378	0.394
Е	9.960	10.360	0.392	0.408
е	2.540	TYP.	0.100	TYP.
H1	6.480	6.880	0.255	0.271
L	12.680	13.280	0.499	0.523
L1	-	3.500	-	0.138
L2	6.500	6.500 REF.		TYP.
ФР	3.080	3.280	0.121	0.129
Q	3.200	3.400	0.126	0.134
Θ1	1°	5°	1°	5°





Attention:

Any and all MJ power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MJ power representative nearest you before using any MJ power products described or contained herein in such applications.

MJ power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MJ power products described or contained herein.

Specifications of any and all MJ power products described or contained herein stipulate the erformance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MJ power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all MJ power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or therwise, without the prior written permission of MJ power Semiconductor CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MJ power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MJ power product that you intend to use.

This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.